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FIG 1A (Prior Art)

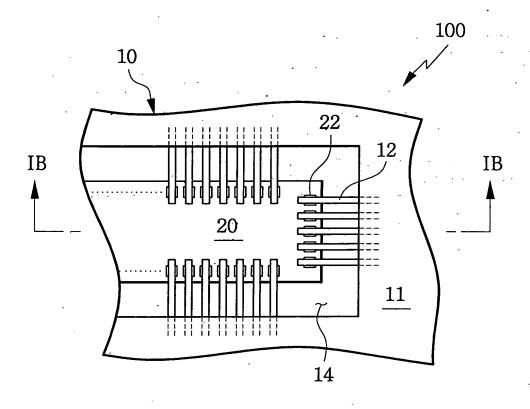
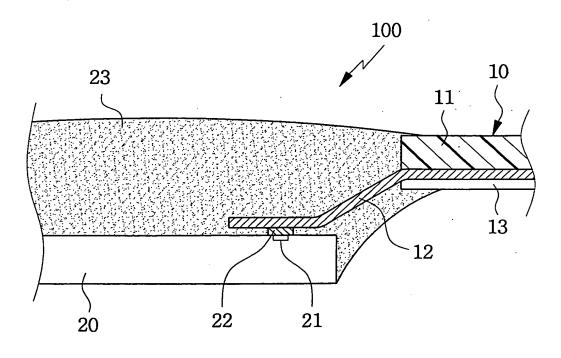


FIG 1B (Prior Art)



Dae-Woo Son, Jin-Hyuk Lee and Kwan-Jai Lee TAPE CIRCUIT SUBSTRATE HAVING WAVY BEAM LEADS AND SEMICONDUCTOR CHIP PACKAGE USING THE SAME Attorney Docket No. 9903-068

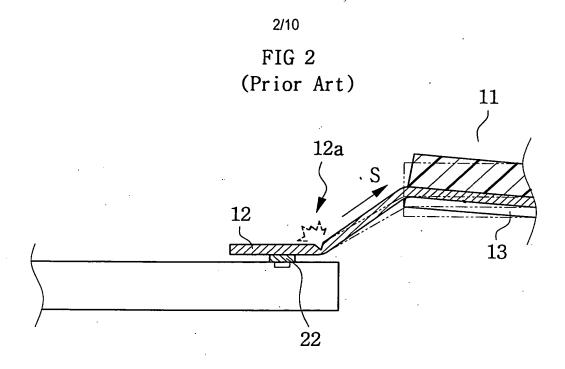
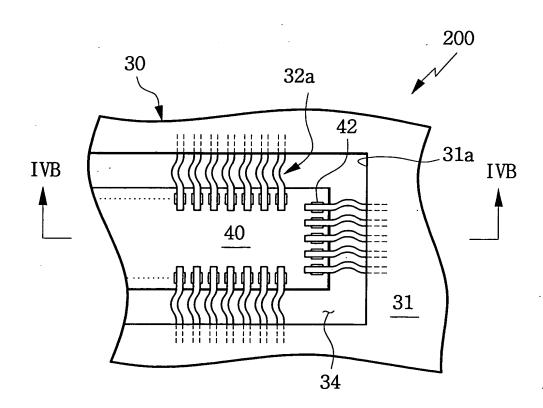
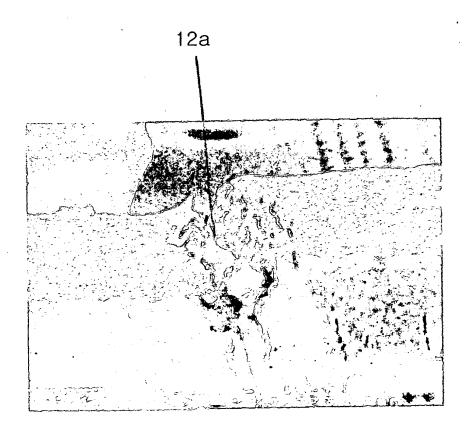


FIG 4A



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FIG 3



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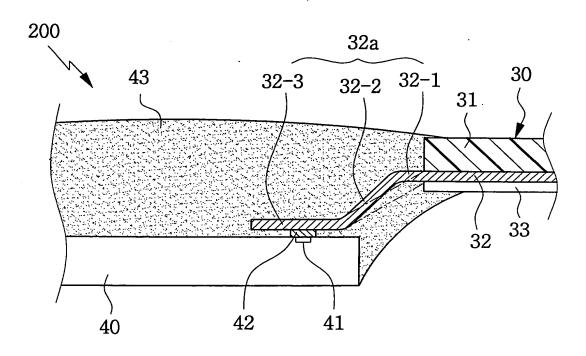
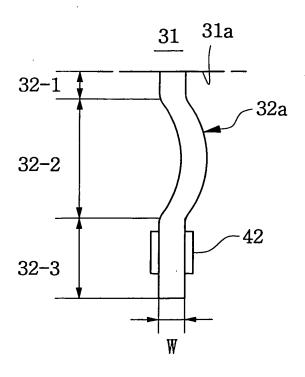
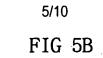
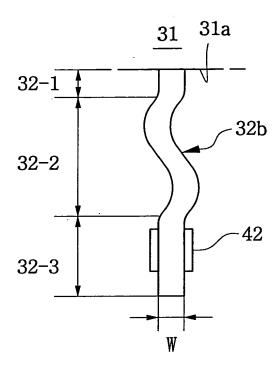


FIG 5A

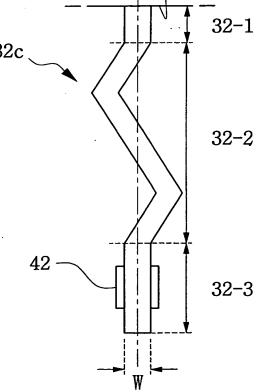






31a 31 32c

FIG 5C



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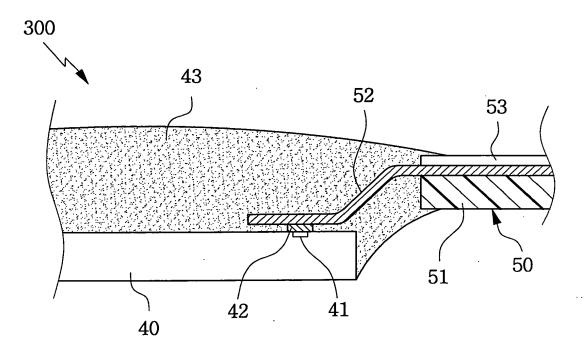
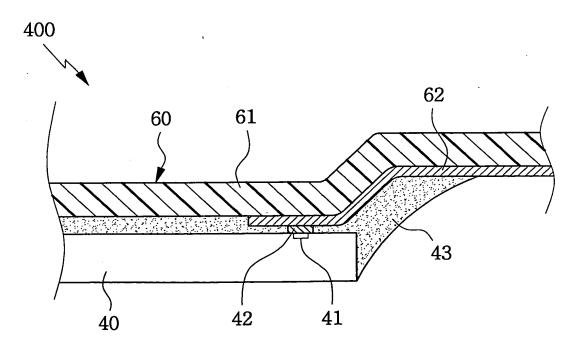


FIG 7



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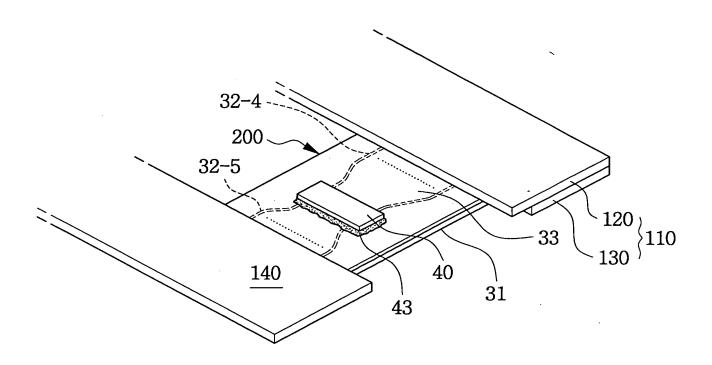
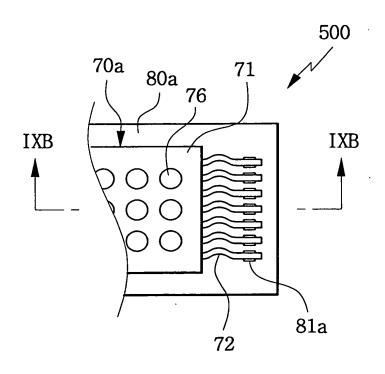


FIG 9A



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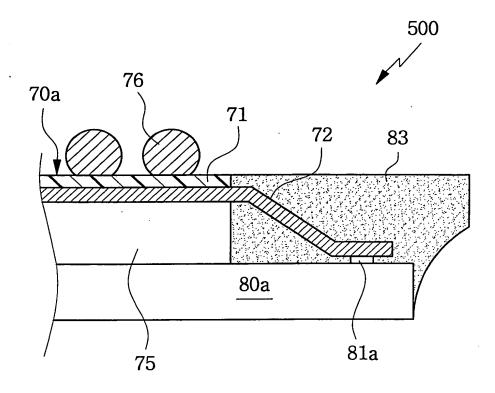
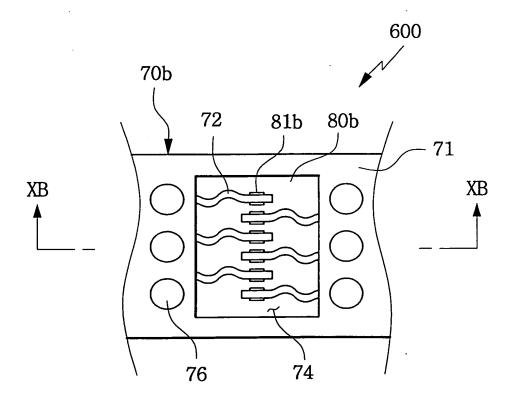


FIG 10A



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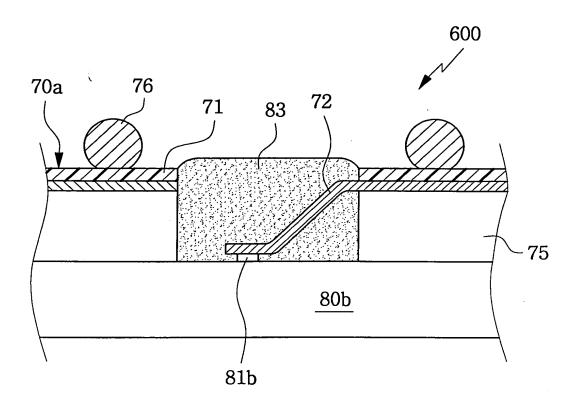
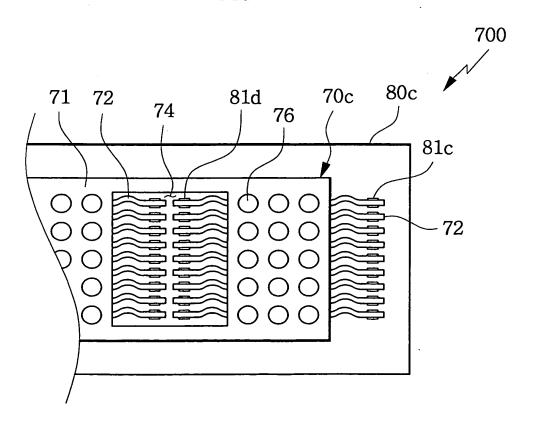


FIG 11



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FIG 12

